

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/17/2022

Details for "TPS76427DBVRG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TPS76427DBVRG4	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DBV 5	1.60X2.90X1.45	15.7

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.029308	100	1000000	0.186356	1864
Sub-Total			0.029308	100	1000000	0.186356	1864
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.183906	75	750000	1.169373	11694
Thermoplastics	Epoxy	85954-11-6	0.061302	25	250000	0.389791	3898
Sub-Total			0.245208	100	1000000	1.559165	15592
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	3.087608	99.28	992800	19.632675	196327
Other Nonferrous Metals and Alloys	Chromium	7440-47-3	0.007775	0.25	2500	0.049438	494
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.007775	0.25	2500	0.049438	494
Zinc and Its Alloys	Zinc	7440-66-6	0.006842	0.22	2200	0.043505	435
Sub-Total			3.11	100	1000000	19.775055	197751
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.186435	95.119898	951199	1.185454	11855
Precious Metals	Gold	7440-57-5	0.001529	0.780102	7801	0.009722	97
Precious Metals	Palladium	7440-05-3	0.008036	4.1	41000	0.051097	511
Sub-Total			0.196	100	1000000	1.246274	12463
Mold Compound							
Other inorganic Materials	Fused Silica	60676-86-0	9.584625	85.000003	850000	60.944209	609442
Other Plastics and Rubber	Carbon Black	1333-86-4	0.033828	0.299999	3000	0.215097	2151
Thermoplastics	Epoxy	85954-11-6	1.657576	14.699998	147000	10.539761	105398
Sub-Total			11.276029	100	1000000	71.699066	716991
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.870339	100	1000000	5.534084	55341
Sub-Total			0.870339	100	1000000	5.534084	55341
Total			15.726884			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.